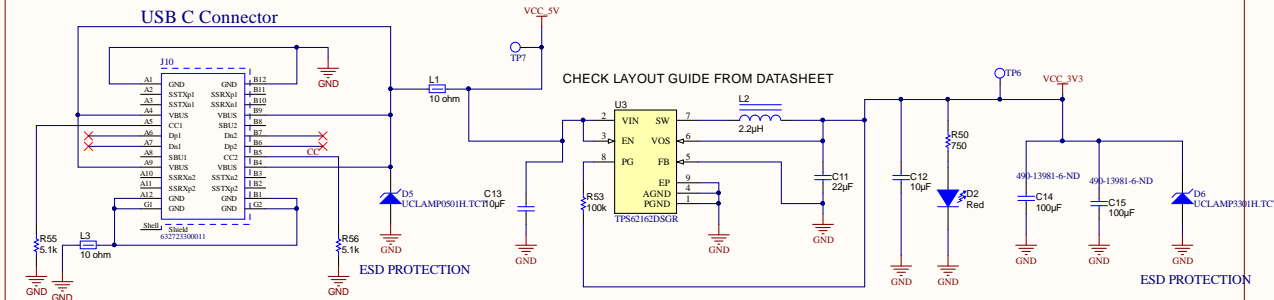


POWER MANAGEMENT



FABRICATION NOTES

UNLESS OTHERWISE SPECIFIED IN THE ECOBEE PURCHASE ORDER, THE FOLLOWING SPECIFICATIONS SHALL APPLY.
ANY DEVIATION SHALL REQUIRE WRITTEN APPROVAL FROM AN ECOBEE REPRESENTATIVE.

- 1. BOARD DATA VIEWED FROM PRIMARY SIDE.
- 2. LATEST REVISIONS SHALL APPLY TO ALL SPECIFICATIONS.
- 3. FABRICATE PCB IN ACCORDANCE WITH IPC-6013C TYPE 2 USING SUPPLIED GERBER OR ODB++ CAD DATA.

Performance Class - Class 2
Installation Usage - Use B

4. FINISH: IMMERSION GOLD

ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH COVERLAY MATERIAL OR OTHER PLATING SHALL BE IMMERSION GOLD (0.000030-0.000090 mm) OVER ELECTROLESS NICKEL (0.001-0.006 mm).

5. LEGEND SHALL BE WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE UV OR EPOXY TYPE INK APPLIED TO THE TOP SIDE OF THE BOARD. THERE SHALL BE NO LEGEND ON ANY SOLDERABLE COMPONENT LAND.

6. ALL ASSEMBLY MATERIALS TO BE RoHS COMPLIANT.

7. THIS IS A NON-WASHABLE ASSEMBLY!

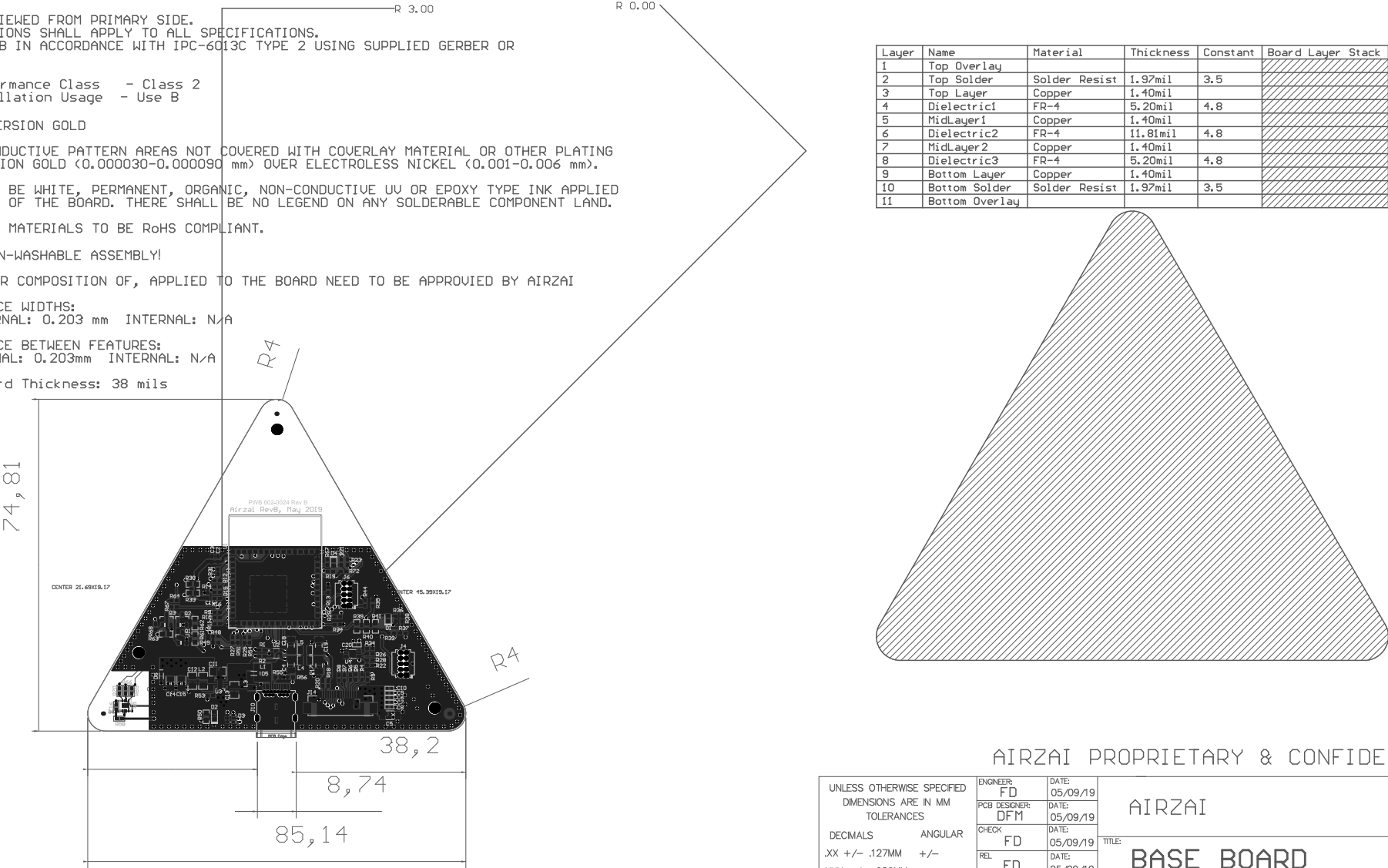
8. ANY LABELS OR COMPOSITION OF, APPLIED TO THE BOARD NEED TO BE APPROVED BY AIRZAI

14. MINIMUM TRACE WIDTHS:
EXTERNAL: 0.203 mm INTERNAL: N/A

15. MINIMUM SPACE BETWEEN FEATURES:
EXTERNAL: 0.203mm INTERNAL: N/A

16. Overall Board Thickness: 38 mils

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	1.97mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	5.20mil	4.8	
5	MidLayer1	Copper	1.40mil		
6	Dielectric2	FR-4	11.81mil	4.8	
7	MidLayer2	Copper	1.40mil		
8	Dielectric3	FR-4	5.20mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	1.97mil	3.5	
11	Bottom Overlay				



AIRZAI PROPRIETARY & CONFIDENTIAL

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM TOLERANCES DECIMALS ANGULAR .XX +/- .127MM +/- .XXX +/- .080MM DO NOT SCALE DRAWING	ENGINEER: FD	DATE: 05/09/19	AIRZAI	TITLE: BASE BOARD	REV: B
	PCB DESIGNER: DFM	DATE: 05/09/19			
	CHECK FD	DATE: 05/09/19			
	REL FD	DATE: 05/09/19			
	SIZE B	SCALE: 1:1	DWG NO: PWB 602-0024 Rev B	SHEET 2 of 2	